

(HT)

( °C )

EDS XRD

(PT)

## Structural evaluation of plasma treated electroless Ni-P coatings

**K. Zangeneh<sup>1</sup> and S.M. Moonirvagefi<sup>2</sup>**

*1. Department of Materials Engineering, Malek-Ashtar University of Technology*

*2. Department of Materials Engineering, Isfahan University of Technology*

**Abstract-** Heat treated electroless Ni-P coatings have high hardness and wear resistance. Traditional heat treatment (1 hr at 400 °C under neutral atmosphere), results in full crystallization of electroless Ni-P coatings. In the present research, electroless Ni-P coatings were treated under conventional as well as plasma conditions. Coating thickness was 5 and 10 micron. Temperature rates and time of the processes were decided to be at 400 °C and 600 °C for 1 and 5 hours, respectively. Thickness, structure, and composition of the coatings were evaluated by optical microscopy, XRD and EDS methods in both heat treatment (HT) and plasma treatment (PT) conditions. It was shown that coating thickness as well as its XRD spectrum (i.e. intensity and breadth of peaks) was different. These disparities were related to sputtering phenomenon, special transformation behaviour, and residual strain in the plasma treated electroless Ni-P coatings. It was also found that chemical composition of the coatings could be altered during plasma process.

**Keywords:** Ni-P coating, Plasma treatment, Phase transformation, Sputtering, Diffraction intensity

pH °C

/ [ ] [ ] [ ]

( / ) /

mbar

Li Wu

Pert-

Ni<sub>7</sub>P<sub>3</sub> Ni<sub>3</sub>P, Ni<sub>5</sub>P<sub>4</sub>

mA

kV

X'MPD

Wierzchon

[ ]

(λ= / ) Cu K<sub>α</sub>

/ s<sup>-1</sup>

Golanski Bielinski

EDS

H<sub>2</sub>/BCl<sub>3</sub>

XL

[ ]

°C

PT HT

/ %Mo AISI

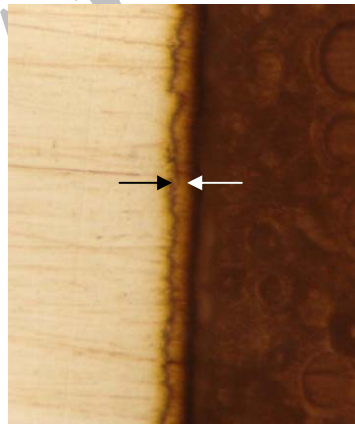
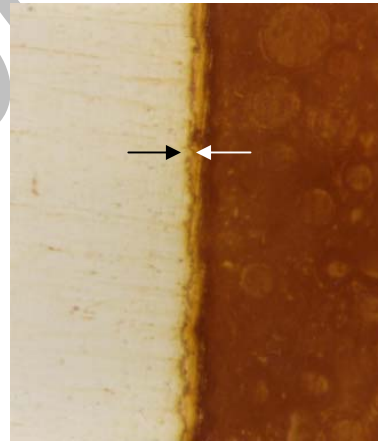
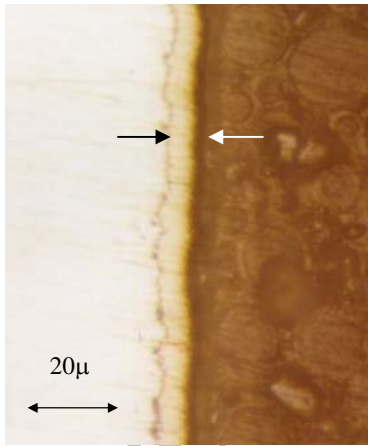
/ %C / %Si / %Mn / %Cr / %Ni

mm

mm

Archive of SID

		(μm)	
(hr)	(°C)		
			/
			/
			/
			/
			/
			/
			/
			/



Keong

[ ]

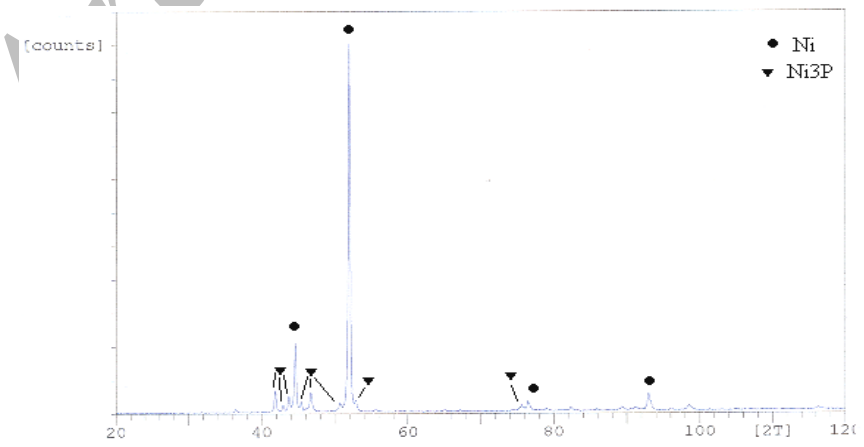
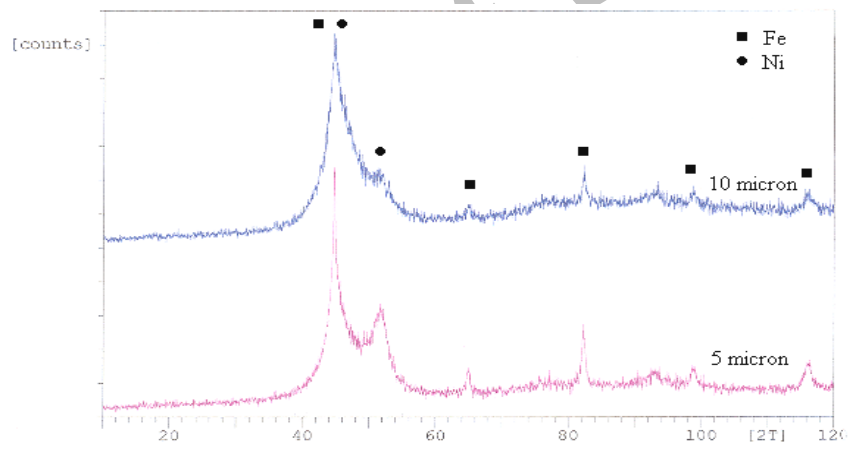
( )

°C

Ni<sub>3</sub>P

XRD

( )



( )

(PT)

(HT)

Ni<sub>3</sub>P

I <sub>total</sub>		I <sub>Ni</sub>		I <sub>Ni3P</sub>		
PT	HT	PT	HT	PT	HT	
						/
						/
						/
						/
						/
						/
						/
						/

(

Ni<sub>3</sub>P

( )

[ ]

Ni<sub>3</sub>P

(HT)

(PT)

Archive of SID

)

(

(I<sub>total</sub>)

)

(

°C

( )

°C

( )

)

(HT)

$\Delta I_t / I_t^{HT}$ (%)	$\Delta I_{Ni} / I_{Ni}^{HT}$ (%)	$\Delta I_{Ni3P} / I_{Ni3P}^{HT}$ (%)	
/	/		/
	/	/	/
	/	/	/
	/	/	/
/	/	/	/
/	/	/	/
/	/	/	/
/	/		/

$\text{kJ}\cdot\text{mole}^{-1}$ )

[ ]

XRD

(  $\text{kJ}\cdot\text{mole}^{-1}$ )

(

EDS

EDS

( )

%

%

$\text{Ni}_3\text{P}$

XRD

)

(

(

EDS

EDS

)

(

$\text{Ni}_3\text{P}$

( )

%

%

$\text{Ni}_3\text{P}$

( )

$\text{Ni}_3\text{P}$

[ ]

EDS

(PT) (HT)

HT	(±%) PT	(±%)		
		PT	HT	
		/	/	/
			/	/
		/	/	/
		/	/	/

XRD

( )  
( ) % (Ni<sub>3</sub>P)

(EDS XRD

Ni<sub>3</sub>P

( ) %

(% ) Ni<sub>3</sub>P

Ni<sub>3</sub>P

XRD

(Average Breadth)

/ /

[ ]

± / (σ)

Ni<sub>3</sub>P

Ni<sub>3</sub>P

(XRD) Ni<sub>3</sub>P :  
 (PT) (HT)

Ni <sub>3</sub> P		%Ni <sub>3</sub> P		
HT	PT	PT	HT	
/	/	/	/	/
/	/	/	/	/
/	/	/	/	/
/	/	/	/	/

[ ]

$$B = [(4e \cdot \text{tg } \theta)^2 + (\lambda/d \cdot \text{Cos } \theta)^2]^{1/2}$$

°C

°C

d e B  
 λ θ

Ni<sub>3</sub>P  
 (%) )

Archive of SID

XRD SEM



(PT)

(HT)

(B<sub>average</sub>)

$\Delta B$	B <sub>average</sub>			$\Delta B$	B <sub>average</sub>		
	PT	HT			PT	HT	
	/	/	/	/	/	/	/
/	/	/	/	/	/	/	/
/	/	/	/	/	/	/	/
/	/	/	/	/	/	/	/

7. T. Wierzchon and P. Bielinski, *Formation and Properties of Multicomponent and Composite Borided Layers on Steel*, Sur. Coat. Tech,73(1995)121-124.
8. D. Golanski, *Numerical Modeling of Residual Stresses in Boride Layers on Steel*, Sur. Eng., (2)(1997)145-148.
9. K. G. Keong, W. Sha and S. Malinov, *Hardness Evaluation of Electroless Nickel-Phosphorus Deposits With Thermal Processing*, Sur. Coat. Tech., (2003)263-274.
10. F. B. Wu, Y. I. Chen and P. J. Peng, *Fabrication, Thermal Stability and Microhardness of Sputtered Ni-P-W Coating*, Sur. Coat. Tech., (2002)232-238.
11. J. L. Vossen and W. Kern, *Thin Film Processes*, Academic Press, (1978)513.
12. L. I. Maissel and R. Glang, *Handbook of Thin Film Technology*, McGraw-Hill Pub,(1970)3-23.
13. Z. Guo, K. G. Keong and W. Sha, *Crystallisation and Phase Transformation Behaviour of Electroless Nickel Phosphorus Platings During Continuous Heating*, J. Alloys Comp,358(2003)112-119.
14. D. T. Gawne and U. Ma, *Structure and Wear Electroless Nickel Coatings*, Mater. Sci. Tech, 3(1987)228-238.
1. K. L. Lin and W. C. Chen, *The Interdiffusion and Interphases Formed Between Electroless Nickel Deposit and Steel Substrate*, Scrip. Metall. Mater, 29(5)(1993)667-672.
2. A. Hugon, *Modification of the Properties of Electroless Nickel-Phosphorus Coatings by Laser Annealing or Melting*, The Min. Met. Mater. Soc.,(1989)71-81.
3. L. Renaud, *Surface Alloys Obtained on Mild Steel by Laser Treatment of Electroless Nickel Coatings*, Acta Metall. Mater., 38,(8)(1990)1547-1553.
4. K. Hanamoto, *Annealing Effects on the Hardening of Electroless Plated Ni-P Layer by Boron Implantation*, Nuc. Instru. Meth. Phys. Res., B145(1998)391-394.
5. J. I. Onate, *Nitrogen Implantation of Tool Steels and Engineering Coatings*, Dissertation Abstracts International, 51(4)(1990)310.
6. Y. Wu and H. Li, *Solute Distribution and Phase Structure of Electroless Ni-P Alloy Layer by Plasma Remelting*, Trans. Mater. Heat Treat. (China), 22(2)(2001)19-22.